

ABSTRACT OF THE DISCLOSURE

Configurations of semiconductor processing chambers to promote consistency of pressure profiles across the surface of the wafer being processed. One aspect of the chamber configuration is a mushroom-shaped wafer support structure with a broad electrode supported by a relatively narrow vertical stem arising from the bottom wall of the chamber. The stem may be centered under the electrode or, optionally, is offset from its center. Services for the electrode are provided via the narrow vertical stem. Another aspect of the chamber configuration is twin processing regions together in a single chamber, evacuated by a single vacuum pump.

ETCHING CHAMBER